BRBAV99WAQ

Rev.A Jul.-2024

DATA SHEET

/ Descriptions

VRW0656 ṂṂ Ƚ ᴁṀ ɥ͡ ‖ ʅ Silicon Diode in a SOT-323 Plastic Package.

/ Features

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Very small plastic SMD package, High switching speed, High Continuous reverse and Repetitive peak reverse voltage, High Repetitive peak forward current, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

/ Applications

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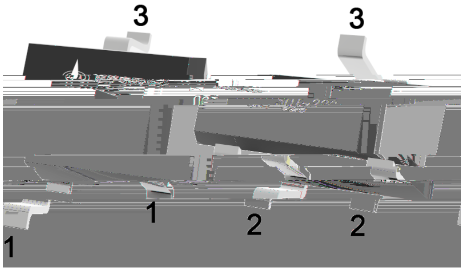
Applications for High-speed switching, surface mounted circuits, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit

/ Pinning



PIN: See Equivalent Circuit.

/ Marking

Marking	QA7

@ ƒ Parameter	… Z Symbol	ƒ › Rating	% y Unit
Repetitive Reverse Voltage	V_{RRM}	85	V
Continuous reverse voltage	V_R	75	V
Continuous forward current	$I_{F(1)}$	150	mA
	$I_{F(2)}$	130	mA
Repetitive peak forward current	I_{FRM}	500	mA
Non-repetitive Peak Forward Current	$I_{FSM(1)(t=1\ S)}$	0.5	A
	$I_{FSM(2)(t=1\ mS)}$	1.0	A
	$I_{FSM(3)(t=1\ S)}$	4.0	A
Power Dissipation	P_D	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range			

F(1)

Ô ? d • Ž ¢ / Electrical Characteristic Curve

Ø ¤ =) ¢ / Package Dimensions

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š WD t … • Ž ¢ (x /) / : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O T M 6

ª ¢ y	Note:
1o• Ä ½ “ † 150 ½200 - k ž • 60 ½120sec;	1.Preheating:150~200 - , Time:60~120sec.
2o• Q › “ † 255 r 5 - k ž • 4 Ò 5 r 0.5sec;	2.Peak Temp.:255 r 5 - , Duration:5 r 0.5sec.
3o•D N ò i Ò 0 , † 2 ½10 - /sec.	3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r 5 - ž • y 10 r 1 sec. Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ˜ E	Units ;>û ¦H	Dimension ;>û p . (unit Æmm^3